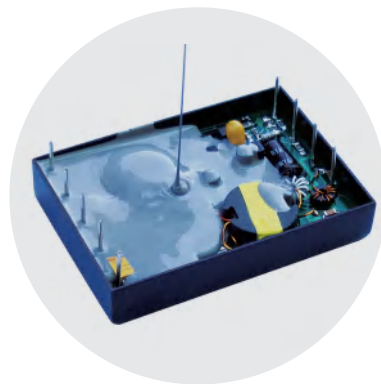




导热灌封胶

THERMAL POTTING

产品介绍 PRODUCT INTRODUCTION

对于一些发热元器件需要的不仅仅是导热，有时候还需要灌封树脂将器件封装起来。导热灌封胶不仅解决了散热问题，而且保护元件不受环境的损害。

For some heating components, we need not only heat dissipation, but also potting resin to encapsulate the components. The heat conduction potting material not only solves the problem of heat dissipation, but also protects the components from environmental damage.

产品特点 PRODUCT FEATURE

- 同时提供含硅和非硅产品
- Provide silicone and non-silicone products
- 高绝缘性
- High insulation
- 适合高湿、腐蚀环境
- Suitable for high humidity and corrosive environment

典型应用 TYPICAL APPLICATION

- 光伏逆变器，接线盒
- Photovoltaic inverter, junction box
- 继电器
- Relay
- 伺服和变频
- Servo and Frequency converter
- 马达
- Motor
- 电池包，车载充电机，充电桩
- Battery pack, OBC, Charging pile

产品参数 PRODUCT PARAMETER

产品型号 Models	导热系数 Thermal Conductivity	密度 Specific Gravity	使用温度 Application Temperature	操作时间 Pot Life	固化时间 Cure Time	体积电阻率 Volume Resistivity	阻燃等级 Flammability Rating	保质期 Shelf Life
	W/m. K	g/cm ³	℃	(@25℃ min)	(@100℃ min)	Ω • cm	UL-94	month
SPO 10	1.0	1.7	-40~150	60	30	10 ¹³	V0	6
SPO 20	2.0	2.7	-40~150	60	30	10 ¹³	V0	6
SPO 30	3.0	3.1	-40~150	60	30	10 ¹³	V0	6
SPO 40	3.6	3.1	-60~200	60	30	10 ¹³	V0	3